

DESCRIPTION

Microsemi – Lowell’s switch modules provide an economical way of achieving a switch function from UHF through Ku band. These switch modules provide broadband, high performance characteristics in a small package. Our catalog parts are basic examples of our capability. We will be glad to explore your specific requirements with the goal of providing custom parts for your needs.

This series of modules meets RoHS requirements per EU Directive 2002/95/EC. The standard terminal finish is gold unless otherwise specified. Consult the factory if you have special requirements.

KEY FEATURES

- Multi Octave Frequency Ranges
- Hermetically Sealed
- Microstrip/Stripline Compatible
- Internal TTL Driver
- RoHS Compliant

IMPORTANT: For the most current data, consult *MICROSEMI*'s website: www.MICROSEMI.com



These devices are ESD sensitive and must be handled use using ESD precautions.

**ABSOLUTE MAXIMUM RATINGS AT 25° C
(UNLESS OTHERWISE SPECIFIED)**

Rating	Symbol	Value	Unit
Storage Temperature	T _{STG}	-55 to +125	°C
Operating Temperature	T _{OP}	-55 to +95	°C
RF CW Power Handling	P _{CW}	10	W

APPLICATIONS/BENEFITS

- Drop in Module
- Broadband (0.5 – 18 GHz)

GUARANTEED ELECTRICAL PARAMETERS @ 25°C (unless otherwise specified)

Model Number	Frequency Range	Insertion Loss (dB) (Max)	Isolation(dB) (Min)	VSWR (Max)	SWITCHING SPEED ¹ (nS)	
					T _{RISE} (Max)	T _{FALL} (Max)
GG71210-01	0.5 - 4.0	0.9	40	1.5:1	50	50
GG71210-02	2.0 - 8.0	1.3	50	1.7:1	50	50
GG71210-03	4.0 - 12.4	1.5	60	1.9:1	50	50
GG71210-04	8.0 - 18.0	1.8	50	2.0:1	50	50
GG71210-05	2.0 - 18.0	1.8	45	2.0:1	50	50

Notes:

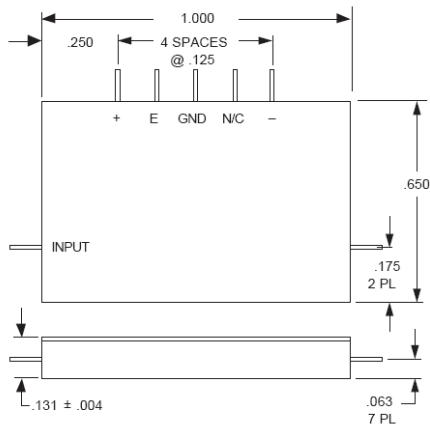
- Switching Speed is measured from the 50% point of the TTL pulse to the 90/10% of the detected RF pulse with a 2 MHz maximum switching rate.
- TTL Driver:
 - Required D.C. Bias: +5v @ +75mA (max) & -8 to -15v @ -50mA (max)
 - Logic: TTL "0" = loss; TTL "1" = isolation

ENVIRONMENTAL

These units are designed to withstand the following environmental conditions without damage.

ENVIRONMENTAL CONDITIONS

TEST	MIL-PRF	METHOD	COND.
Internal Visual	883	2017	--
Stabilization Bake	883	1008	B
Thermal Cycle	883	1010	B
Constant Acceleration	883	2001	1 (Y1 Axis)
Seal – Fine Leak	883	1014	A1
Seal – Gross Leak	883	1014	C1
External Visual	883	2009	--

OUTLINE 210014

NOTES

- All pins are 0.012 ± 0.001" dia, 0.100" (min) long. May be supplied with tabs, 0.025 ± 0.01 x 0.006 ± 0.002, upon request.
- Tolerance on 3 place decimal, ± 0.003" unless otherwise specified.
- Case and leads gold plated per MIL-G-45204, Type 3, Grade A 50 μinch (min).